

Method for Protecting the Redistribution Layer on Wafers/Chips

ABSTRACT OF THE DISCLOSURE

The invention relates to a method for protecting the redistribution layer on wafers/chips, which preferably comprises a structure constructed from a seed layer, a layer of copper situated on the seed layer, a nickel layer arranged thereon, and a gold layer covering the latter. The wafer (4) provided with the redistribution layer (1) is covered on its entire surface with an organic protective layer (12), e.g., made of BTA (benzotriazole), Gliccoat or Preventol®, which protects the redistribution layer (1) from corrosion and oxidation in that it produces a dense covering of the metal surface of the redistribution layer (1) through chemical bonding.